

MA22D15

Silicon epitaxial planar type

For high frequency rectification

■ Features

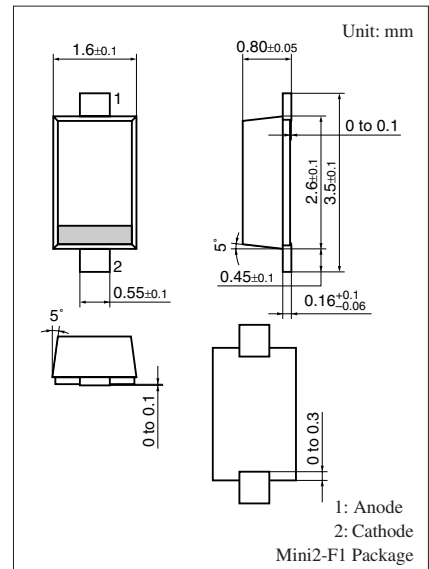
- $I_{F(AV)} = 1$ A rectification is possible
- Low forward voltage V_F
- Low reverse current I_R

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Repetitive peak reverse voltage	V_{RRM}	25	V
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Non-repetitive peak forward surge current *2	I_{FSM}	20	A
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Mounted on a alumina PC board

*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



Marking Symbol: 3R

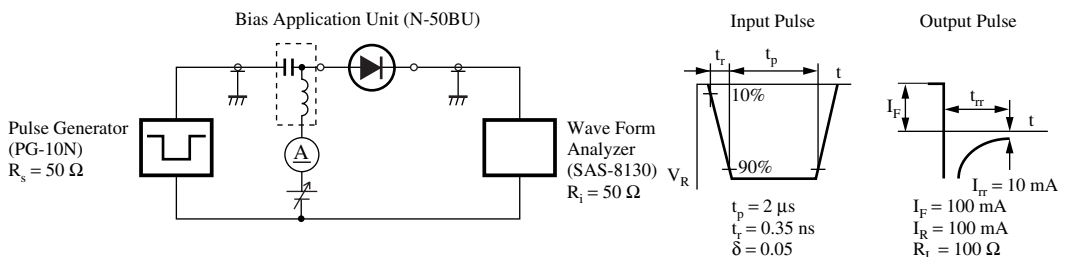
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

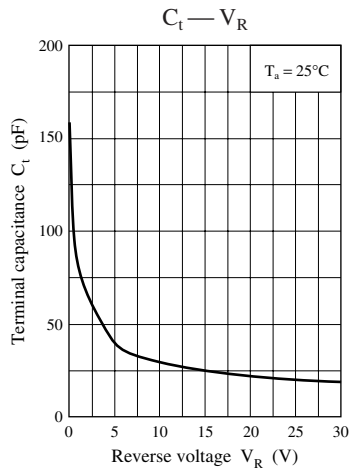
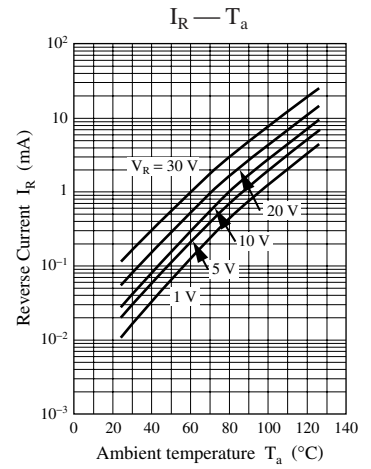
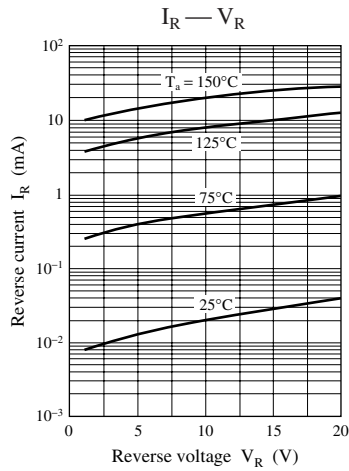
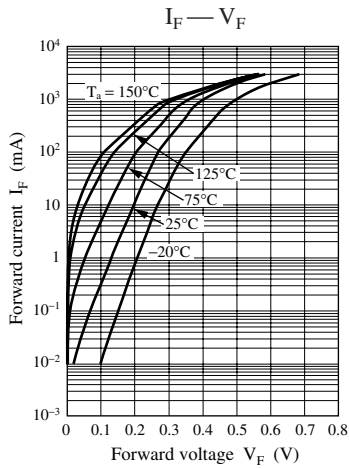
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 1.0$ mA		0.40	0.43	V
Reverse current	I_R	$V_R = 20$ V			100	μA
Terminal capacitance	C_t	$V_R = 10$ V, $f = 1$ MHz		30		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA $I_{Tr} = 10$ mA, $R_L = 100 \Omega$		10		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. *: t_{rr} measuring instrument





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